

REMARKS/ARGUMENTS

By the above, claims 1, 6 and 7 have been amended and claim 5 has been canceled. Generally stated, claims 6 and 7 have been amended to depend on claim 1 and the limitations of cancelled claim 5 have been incorporated into claim 1, along with other limitations. Applicants assert that the amendments do not present new matter because they are support by the originally filed specification, including the figures. Entry of the above amendments and reconsideration of the present application is respectfully requested.

In the Office Action, claim 1 was objected to because “the correction” and “the object side” lacked proper antecedent basis. To this end, claim 1 has been amended to overcome these objections. Accordingly, withdrawal of the objections is respectfully requested.

Also in the Office Action, previously presented claim 5, which has been incorporated into claim 1, was rejected under 35 U.S.C. § 103 as being unpatentable over U.S. Patent Publication No. 2003/0003383 to Van Der Werf et al. in view of U.S. Patent Publication No. 2003/0090640 to Fujisawa et al.

Applicants note, however, that in Fujisawa the wafer is tilted in order to ensure that the wafer surface to be exposed is completely within the image plane of the projection lens 103. This is illustrated in figures 3a to 3c (for a curved wafer) and in figures 12a to 12c (for a planer wafer), and explained in paragraphs 6, 7 and 64. There is no teaching or suggestion in Fujisawa that tilting the wafer could also be used to correct distortion. Instead, distortion is solely corrected by shifting and tilting lens elements within the projection lens 103 as shown in paragraph 66 of Fujisawa.

As currently claimed by the Applicants, tilting of the wafer corrects a specific type of distortion under specific circumstances, namely a substantially linear distortion with two-fold symmetry and in the case of a projection lens being non-telecentric on the object side and having an extra-axial field region on an image plane, as it is recited in claim 1. References Van Der Werf and Fujisawa do not contain any motivation that, under such circumstances, tilting of the wafer could be used to correct a substantially linear distortion with two-fold symmetry in an extra-axial field region of the image plane.

In view of the above, Applicants respectfully submit that the pending claims are in condition for allowance and requests withdrawal of the rejections. Should anything further be required, a telephone call to the undersigned, at (312) 226-1818, is respectfully invited.

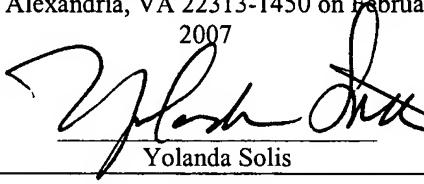
Respectfully submitted,

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Dated: February 5, 2007

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CERTIFICATE OF MAILING	
I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope Addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on February 5, 2007	
 Yolanda Solis	